

# HAT2208R

## Silicon N Channel Power MOS FET Power Switching

REJ03G1595-0200

Rev.2.00

Oct 15, 2007

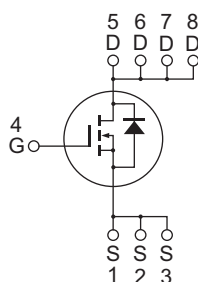
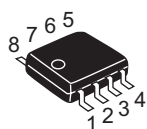
### Features

- High speed switching
- Capable of 4.5 V gate drive
- Low drive current
- High density mounting
- Low on-resistance

$R_{DS(on)} = 19.0 \text{ m}\Omega$  typ. (at  $V_{GS} = 10 \text{ V}$ )

### Outline

RENESAS Package code: PRSP0008DD-D  
(Package name: SOP-8<FP-8DAV>)



1, 2, 3 Source  
4 Gate  
5, 6, 7, 8 Drain

### Absolute Maximum Ratings

( $T_a = 25^\circ\text{C}$ )

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{DSS}$	30	V
Gate to source voltage	$V_{GSS}$	$\pm 20$	V
Drain current	$I_D$	9	A
Drain peak current	$I_{D(pulse)}$ <sup>Note 1</sup>	72	A
Body-drain diode reverse drain current	$I_{DR}$	9	A
Avalanche current	$I_{AP}$ <sup>Note 2</sup>	9	A
Avalanche energy	$E_{AR}$ <sup>Note 2</sup>	8.1	mJ
Channel dissipation	$P_{ch}$ <sup>Note 3</sup>	2.0	W
Channel to ambient thermal impedance	$\theta_{ch-a}$ <sup>Note 3</sup>	62.5	$^\circ\text{C}/\text{W}$
Channel temperature	$T_{ch}$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Notes: 1.  $PW \leq 10 \mu\text{s}$ , duty cycle  $\leq 1\%$

2. Value at  $T_{ch} = 25^\circ\text{C}$ ,  $R_g \geq 50 \Omega$

3. When using the glass epoxy board (FR4 40 x 40 x 1.6 mm),  $PW \leq 10\text{s}$

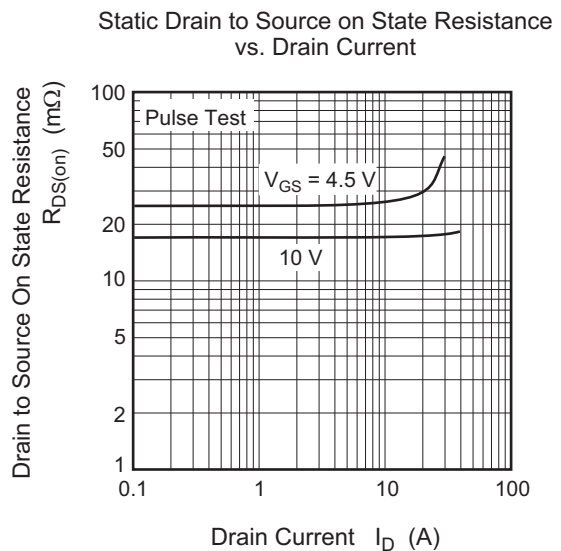
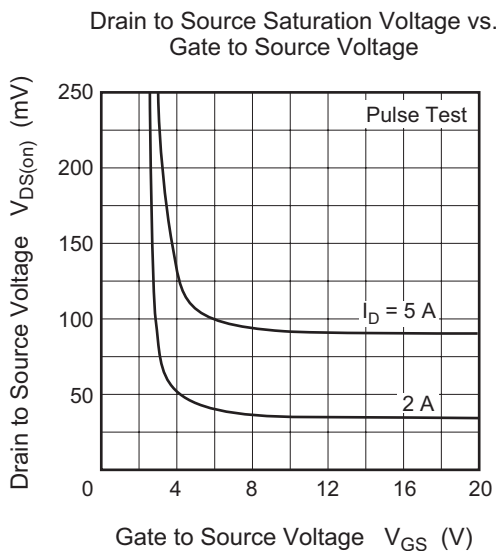
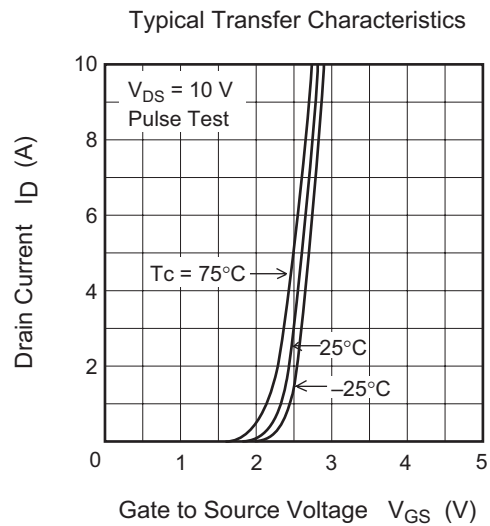
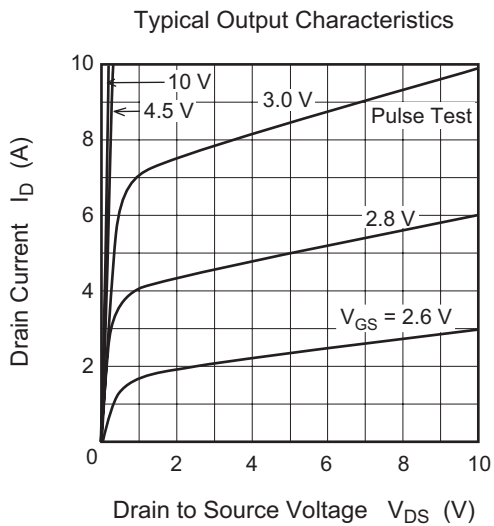
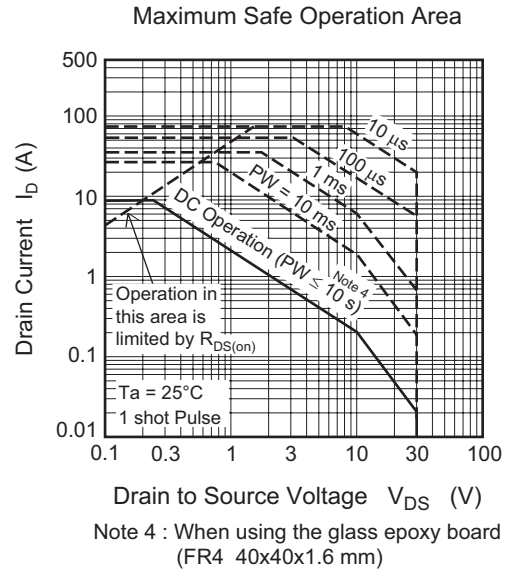
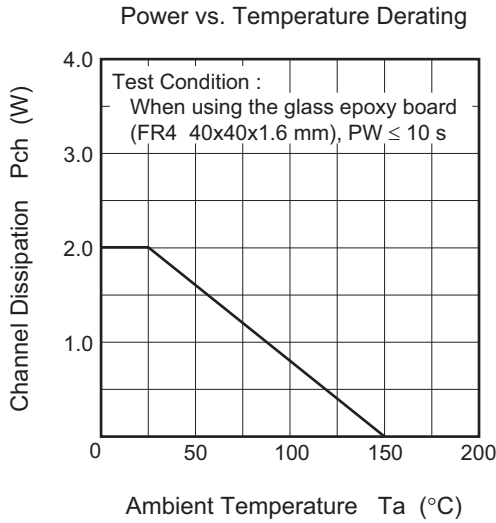
## Electrical Characteristics

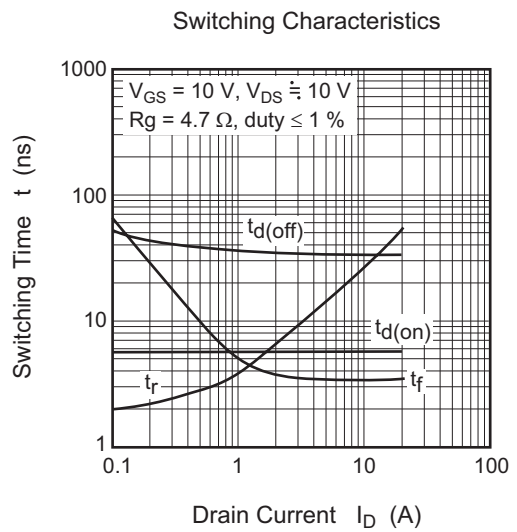
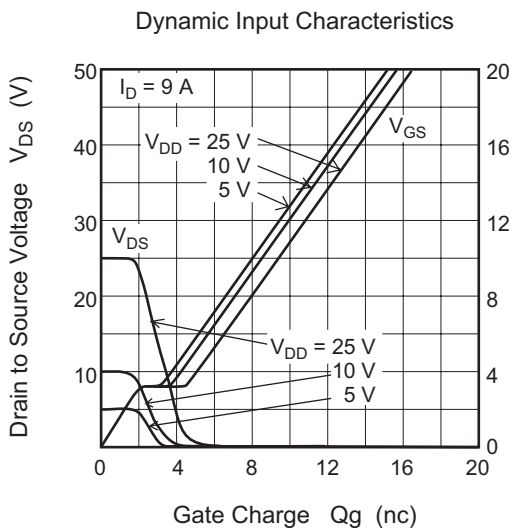
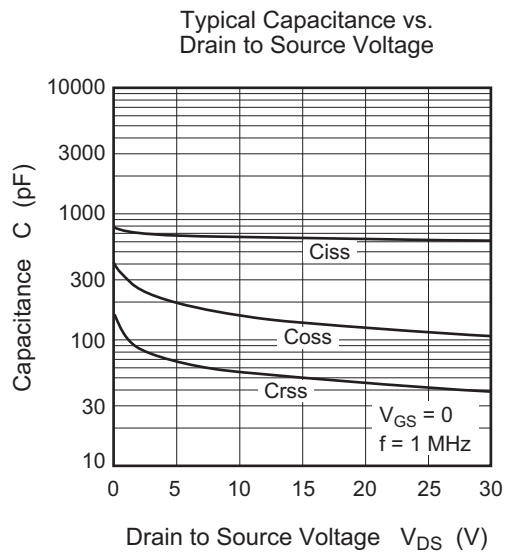
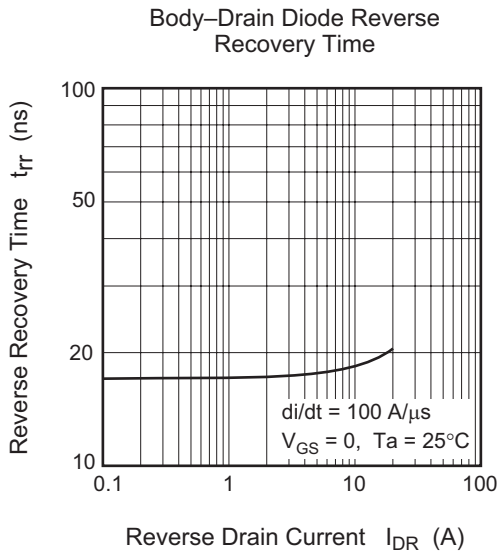
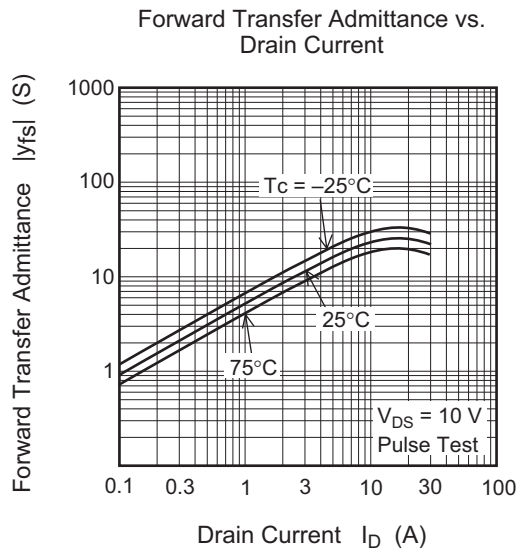
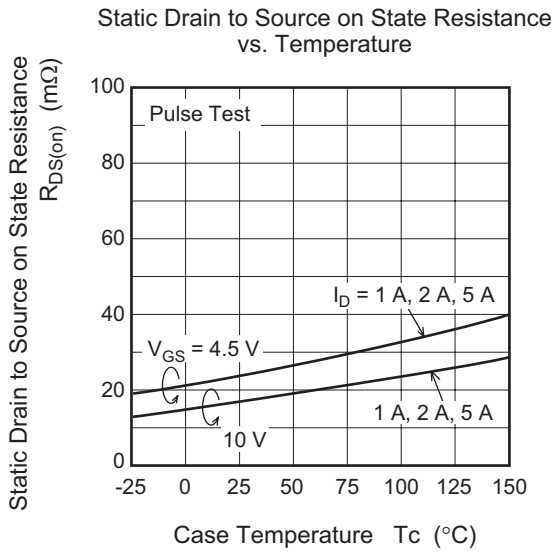
(Ta = 25°C)

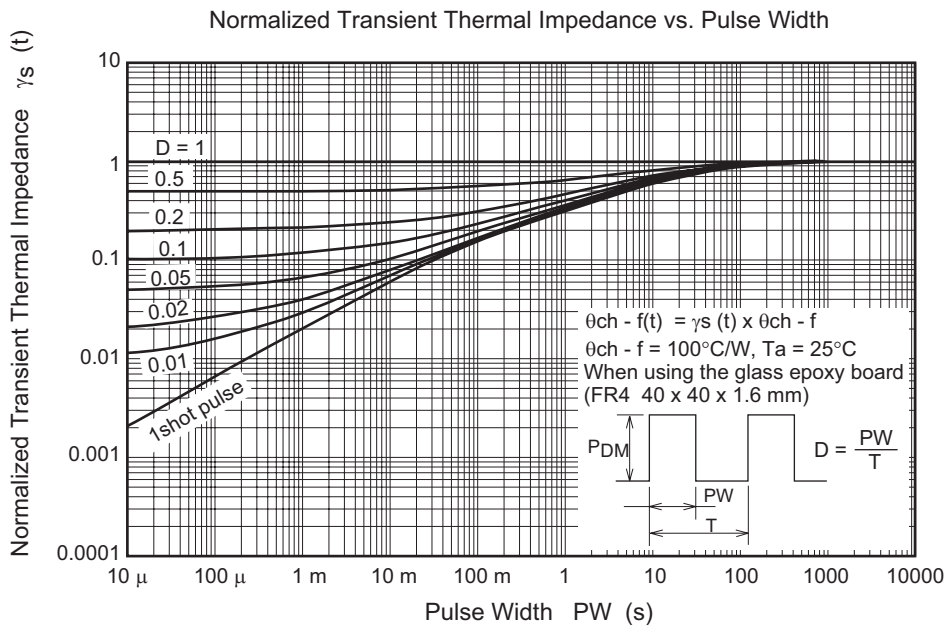
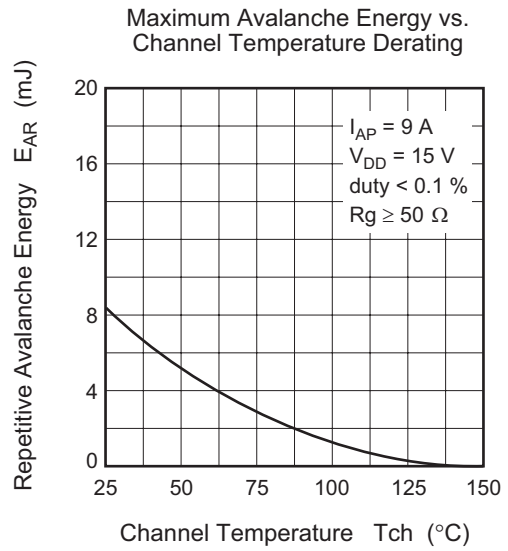
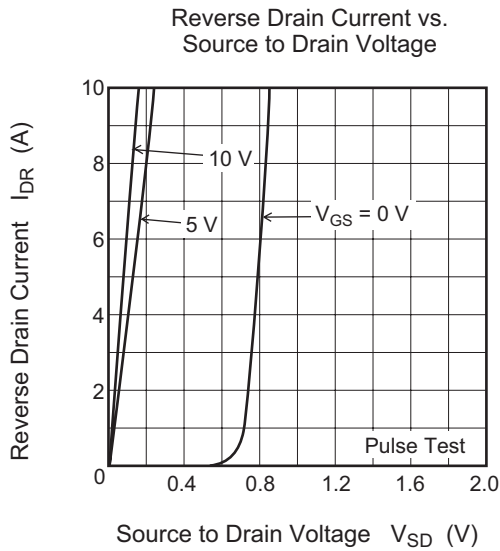
Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	30	—	—	V	$I_D = 10 \text{ mA}$ , $V_{GS} = 0$
Gate to source leak current	$I_{GSS}$	—	—	$\pm 0.1$	$\mu\text{A}$	$V_{GS} = \pm 20 \text{ V}$ , $V_{DS} = 0$
Zero gate voltage drain current	$I_{DSS}$	—	—	1	$\mu\text{A}$	$V_{DS} = 30 \text{ V}$ , $V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	—	2.5	V	$V_{DS} = 10 \text{ V}$ , $I_D = 1 \text{ mA}$
Static drain to source on state resistance	$R_{DS(on)}$	—	19	24	$\text{m}\Omega$	$I_D = 4.5 \text{ A}$ , $V_{GS} = 10 \text{ V}$ <sup>Note4</sup>
	$R_{DS(on)}$	—	24	35	$\text{m}\Omega$	$I_D = 4.5 \text{ A}$ , $V_{GS} = 4.5 \text{ V}$ <sup>Note4</sup>
Forward transfer admittance	$ y_{fs} $	9.5	16	—	S	$I_D = 4.5 \text{ A}$ , $V_{DS} = 10 \text{ V}$ <sup>Note4</sup>
Input capacitance	$C_{iss}$	—	630	—	pF	$V_{DS} = 10 \text{ V}$
Output capacitance	$C_{oss}$	—	160	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	$C_{rss}$	—	56	—	pF	$f = 1 \text{ MHz}$
Gate Resistance	$R_g$	—	1.1	—	$\Omega$	
Total gate charge	$Q_g$	—	4.4	—	nC	$V_{DD} = 10 \text{ V}$
Gate to source charge	$Q_{gs}$	—	2.2	—	nC	$V_{GS} = 4.5 \text{ V}$
Gate to drain charge	$Q_{gd}$	—	1.4	—	nC	$I_D = 9 \text{ A}$
Turn-on delay time	$t_{d(on)}$	—	5.8	—	ns	$V_{GS} = 10 \text{ V}$ , $I_D = 4.5 \text{ A}$
Rise time	$t_r$	—	15	—	ns	$V_{DD} \cong 10 \text{ V}$
Turn-off delay time	$t_{d(off)}$	—	34	—	ns	$R_L = 2.22 \Omega$
Fall time	$t_f$	—	3.5	—	ns	$R_g = 4.7 \Omega$
Body–drain diode forward voltage	$V_{DF}$	—	0.84	1.10	V	$I_F = 9 \text{ A}$ , $V_{GS} = 0$ <sup>Note4</sup>
Body–drain diode reverse recovery time	$t_{rr}$	—	18	—	ns	$I_F = 9 \text{ A}$ , $V_{GS} = 0$ $di_F/dt = 100 \text{ A}/\mu\text{s}$

Notes: 4. Pulse test

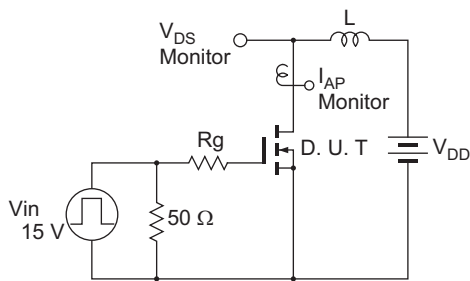
Main Characteristics



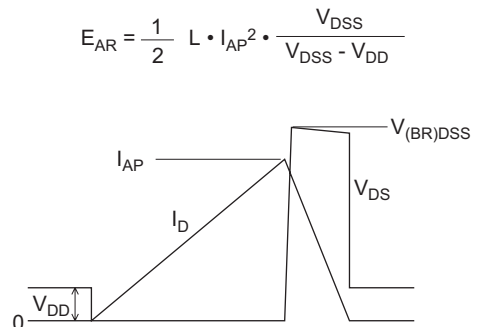


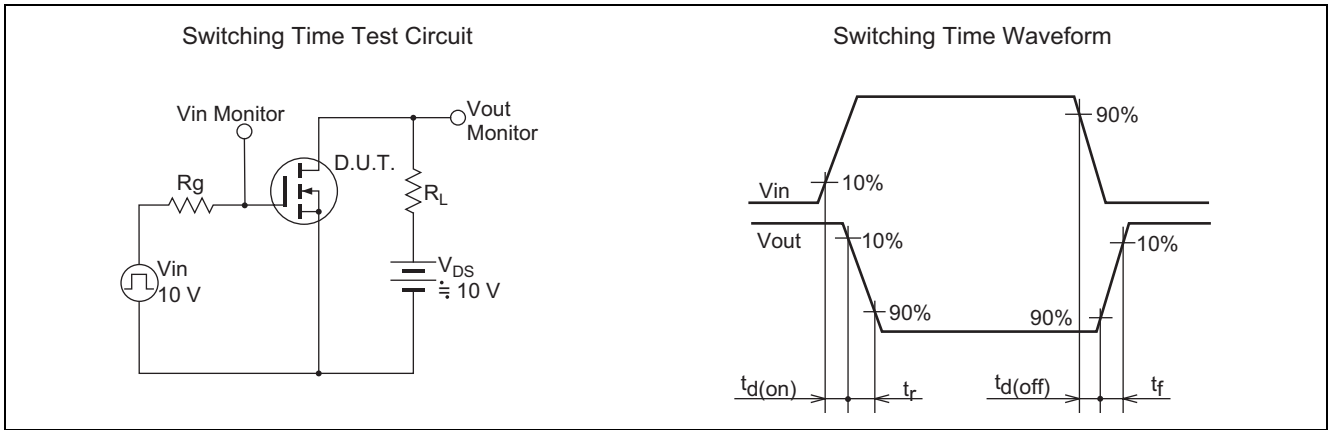


Avalanche Test Circuit

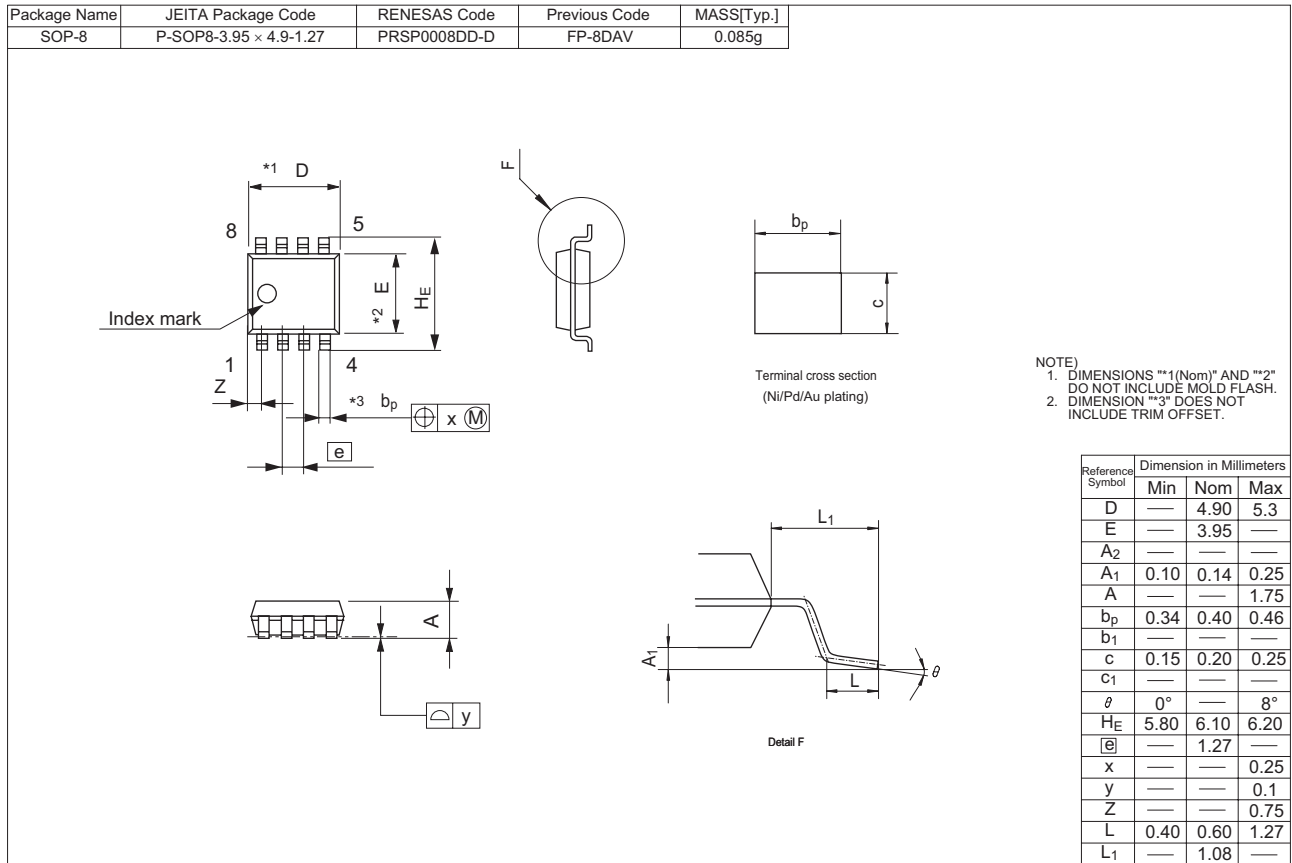


Avalanche Waveform





### Package Dimensions



### Ordering Information

Part Name	Quantity	Shipping Container
HAT2208R-EL-E	2500 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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